## ABSTRACT OF THE DISCLOSURE

A semiconductor device having a plurality of electrothermal conversion elements and a plurality of switching elements for flowing current through the electrothermal conversion elements, respectively 5 formed on a semiconductor substrate of a first conductivity type, wherein each of the switching elements is an insulated gate field effect transistor including: a first semiconductor region of a second 10 conductivity type opposite to the first conductivity type, the first semiconductor region being formed on a principal surface of the semiconductor substrate, a second semiconductor region of the first conductivity type for providing a channel region, the second 15 semiconductor region being formed adjacent to the first semiconductor region, a source region of the second conductivity type formed in a surface layer of the second semiconductor region, a drain region of the second conductivity type formed in a surface 20 layer of the first semiconductor region, and a gate electrode formed on a gate insulating film on the channel region, and a resistivity of the semiconductor substrate is 5 to 18  $\Omega$ cm, and the first semiconductor region has a depth of 2.0 to 2.2  $\mu m$ 25 along a depth direction of the semiconductor substrate and an impurity concentration of  $1 \times 10^{14}$  to  $1 \times 10^{18} / \text{cm}^3$ .